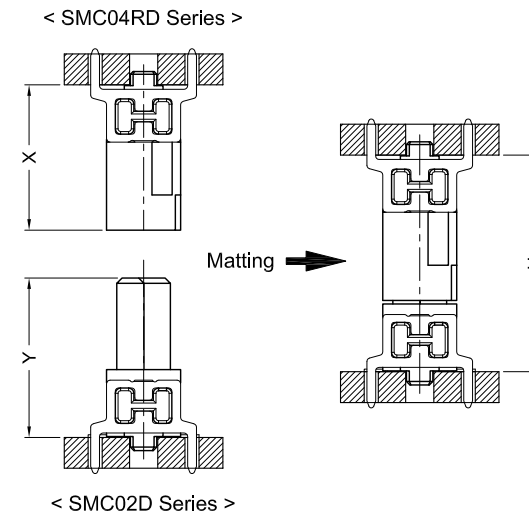


**Specification**

Insulator Material: High Temp. Thermoplastic, UL94V-0.  
 Contact Material: Phosphor Bronze.  
 Board Lock Material: Brass.  
 Contact Plating: Au (1 $\mu$ " / 5 $\mu$ " / 30 $\mu$ " Min.) on Contact Area.  
 Au (1 $\mu$ " Min.) or Sn (100 $\mu$ " Min.) on Soldertail.  
 Nickle (Contact-80 $\mu$ " Min. / Soldertail-50 $\mu$ " Min.)  
 Board Lock Plating: Sn(100 $\mu$ " Min.) over Nickel (40 $\mu$ " Min.)  
 Current Rating: 1.7A Max.  
 Contact Resistance: 25 Milliohms Max.  
 Insulator Resistance: 1000 Megohms Min.  
 Dielectric Withstanding: 500V DC for 1 Minute.  
 Operating Temperature: -55°C ~ +125°C.  
 Max. Processing Temp.: 230°C for 30~60 seconds.  
 260°C for 10 seconds.

Connector Height		Stacking Height
X(SMC04RD)	Y(SMC02D)	H(Mating)
6.75	6.25	8.0-9.5
	9.05	10.8-12.3
8.25	13.65	15.4-16.9
	6.25	9.5-11.0
9.85	9.05	12.3-13.8
	13.65	16.9-18.4
9.85	6.25	11.1-12.6
	9.05	13.9-15.4
	13.65	18.5-20.0



DR.	Shun	CHK.	Ren	APP.	Peter
REV.	New Version		2021,05,11		
REV.	DESCRIPTION	DATE			



TOLERANCE (UNLESS SPECIFIED)  
 X.X = ±0.25  
 X.XX = ±0.15  
 X.XXX = ±0.05  
 ANG. = ±2°



TITLE: 1.27 SMC Female Connector  
 Dual Row Vertical SMT Type  
 (Board Lock Through-Hole)

DWG NO. SMC02D-C

SHEET 2 / 2  
 REV. A